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5C180 48-MACROCELL CMOS PLD

- High-Performance LSI Semicustom Logic Alternative for TTL and 74HC SSI and MSI Logic
- 48 Macrocells with Programmable I/O Architecture; up to 64 Inputs (16 Dedicated, 48 I/O) or 48 Outputs
- High Speed t_{PD} (max) 70 ns, 20.8 MHz Pipelined, 16.1 MHz w/Feedback
- Dual Feedback Signals Allowing I/O Pins to Be Used for Buried Logic and Dedicated Input
- Programmable Clock System with Four Synchronous Clocks as well as Asynchronous Clocking Option on All Registers
- Programmable Registers. Can Be Configured as D, T, SR or JK Types with Individual Reset Controls
- Low Power; 100 μ W Typical Standby Dissipation
- Programmable "Security Bit" Allows Total Protection of Proprietary Designs
- 100% Generically Tested Logic Array
- 68-Pin J-Lead Chip Carrier
(See Packaging Spec., Order #240800-001, Package Type N)
- 100% Compatible with EP1800

The Intel 5C180 PLD (Programmable Logic Device) is a CMOS, 48-macrocell, general-purpose PLD. This user-customizable Logic Device is available in a 68-pin PLCC package and has the benefits of low power and increased flexibility.

The 5C180 PLD uses CMOS EPROM (floating gate) cells as logic control elements instead of fuses. Use of Intel's advanced CMOS II-E EPROM process technology enables greater logic densities to be achieved with superior speed and power performance. The EPROM technology enables these devices to be 100% factory tested by the programming and the erasure of all the EPROM logic control elements in the device.

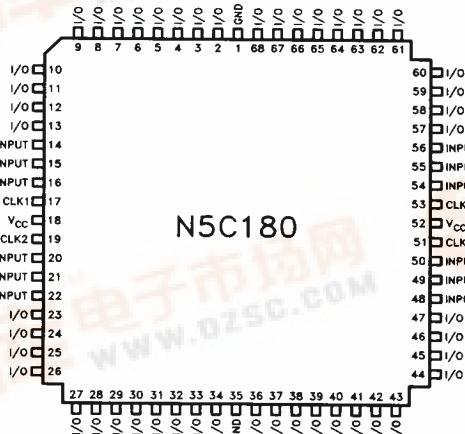


Figure 1. Pin Configurations

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INTRODUCTION

The architecture of the 5C180 is based on the "Sum of Products" PLA (Programmable Logic Array) structure with a programmable AND array feeding into a fixed OR array. The 48 macrocells of the 5C180 can be partitioned into 4 identical quadrants each containing 12 macrocells. This device makes use of a segmented PLA structure with local and global bus structures to provide for increased performance and greater device utilization. The 5C180 has unique architectural features that allow programming of all 48 registers to D, T, SR or JK configurations without sacrificing product terms. These registers can be either clocked asynchronously or in banks with four synchronous clocks. In addition, the 16 global macrocells have two independent feedback paths to the array that allow for buried logic implementation together with use of the I/O pin for input functions.

ARCHITECTURE DESCRIPTION

Externally, the 5C180 provides 12 dedicated data inputs, 4 synchronous clock inputs, and 48 I/O pins which may be individually programmed for input, output, or bi-directional operation.

The Block Diagram is shown in Figure 2 with pin numbers for the PLCC package. The internal architecture is organized in familiar sum-of-products (AND-OR) structure. The 5C180 houses a total of 480 product terms distributed among 48 Macrocells. The basic Macrocell structure is shown in Figure 3. Input and feedback signals are selectively connected to product terms via EEPROM cells. The output of the AND array feeds a fixed OR gate to produce sum-of-products logic. The final output may be combinatorial or registered, programmed active high or low. Combinatorial, registered, or pin feedback is also user-defined.

The 5C180 is partitioned into 4 identical quadrants. Each quadrant contains 12 Macrocells. Input signals to the Macrocells come from the 5C180 Local and Global bus structures. These two buses comprise an 88-input AND array for each quadrant. The output of each Macrocell feeds an I/O Architecture Control Block which contains output and feedback selection.

Four dedicated clock inputs provide synchronous clock signals to the 5C180 internal registers. There is one synchronous clock per quadrant. Therefore each clock signal controls a bank of 12 registers. CLK1 may be connected to registers in Macrocells 1-12, CLK2 with Macrocells 13-24, CLK3 with Macrocells 25-36, and CLK4 with Macrocells 37-48. With synchronous clocks, the flip-flops are positive edge triggered. Both true and complement signals for each dedicated clock input may also be used

within the AND array. All 48 internal registers may be individually programmed for synchronous or asynchronous clocking. Asynchronous clocking is possible via a Macrocell product term. Clock inputs not used for synchronous clock signals may be used as global bus inputs.

Invert Select EEPROM Bit

The Invert Select EEPROM bit is used to invert the product term input into the register. This applies to all inputs including double inputs on JK and SR registers. The invert option allows the highest possible logic utilization by use of deMorgan logic inversion.

At each intersecting point in the logic array there exists an EEPROM-type programmable connection. Initially, all connections are complete. This means that both the true and complement of all inputs are connected to each product term. Connections are opened during the programming process. Therefore any product term can be connected to the true or complement of any input. When both the true and complement connections of any input are left intact, a logical false results on the output of the AND gate. If both the true and complement connections of any input are programmed open, then a logical "don't care" results for that input. If all inputs for a product term are programmed open, then a logical true results on the output of the AND gate.

BUS STRUCTURE

Input and feedback signals are connected to each 5C180 Macrocell via a Local and Global Bus. Figure 4 shows the Macrocell-Bus interface for Quadrant D. The Global Bus contains 64 input signals while the Local Bus has 24.

Within the 5C180 Macrocell, the product-terms share the entire bus structure. Therefore, a logical AND of any of the variables (or their complements) that is present on the buses may be produced by each product term.

All quadrants share the same Global Bus. Inputs to the bus come from the true and complement signals of the 12 dedicated data inputs, 4 clock inputs, and the 16 Global Macrocell pin feedback signals.

Each quadrant has its own Local Bus. Inputs to this bus come from the 12 quadrant Macrocells. For the eight Local Macrocells, the signals can be either from the Macrocell internal logic or from the pin. For the four Global Macrocells, the signals come from the Macrocell internal logic only.

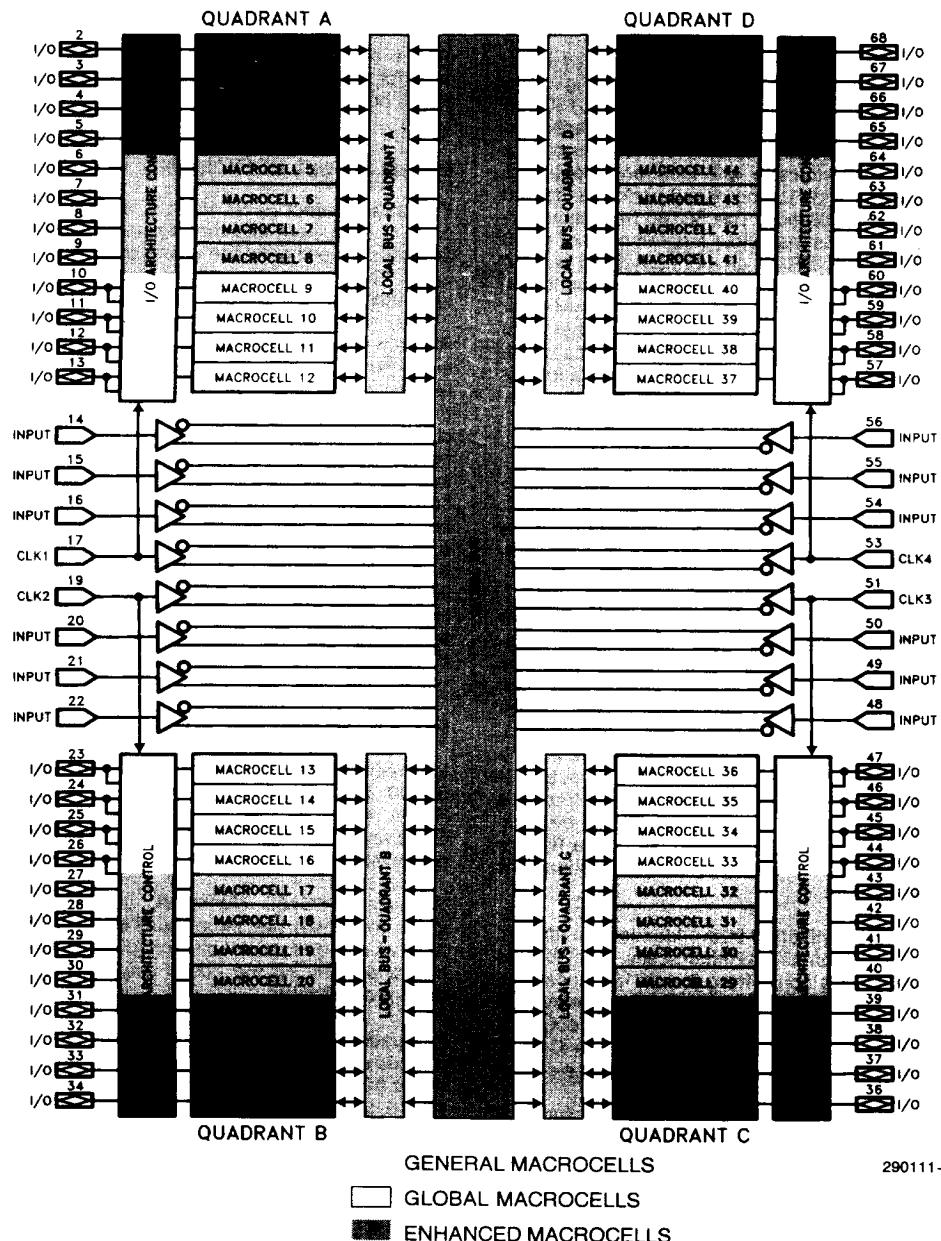


Figure 2. 5C180 Block Diagram—PLCC Package

Table 1 summarizes the Macrocell interconnect.

Table 1. Macrocell Interconnect

	Pin #	Macro-cell #	Feedback Structure	Feedback Interconnect
Quad A	2-9 10-13	1-8 9-12	Local Local Global	Quad A Quad A All
Quad B	23-26 27-34	13-16 17-24	Local Global Local	Quad B All Quad B
Quad C	36-43 44-47	25-32 33-36	Local Local Global	Quad C Quad C All
Quad D	57-60 61-68	37-40 41-48	Local Global Local	Quad D All Quad D

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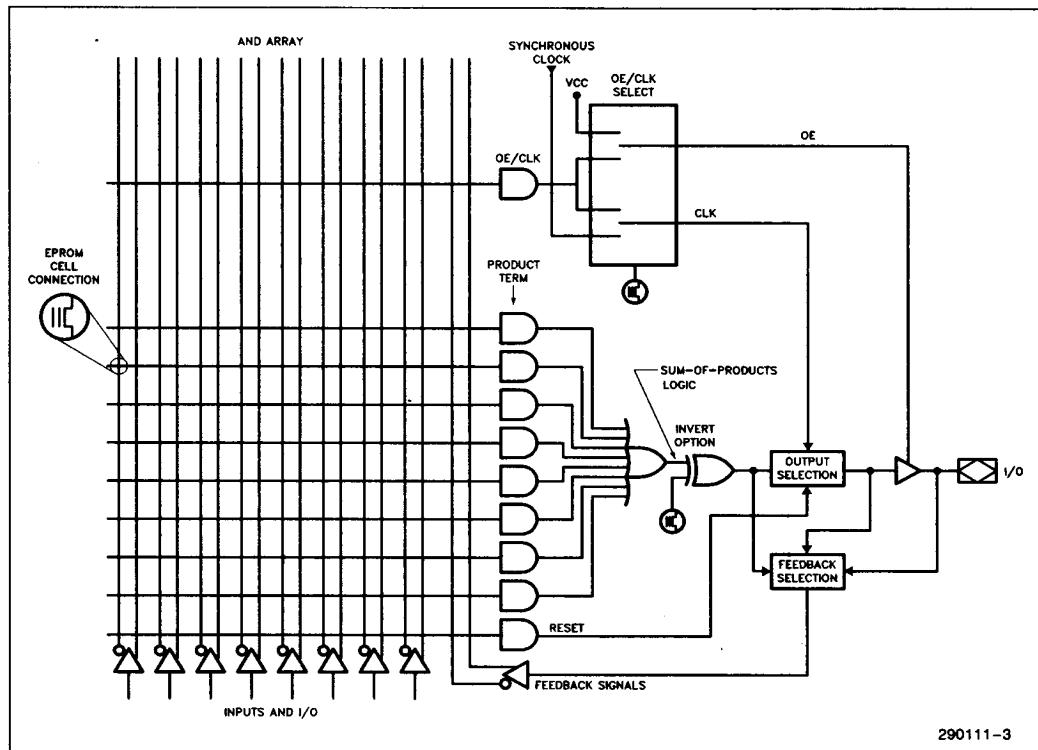
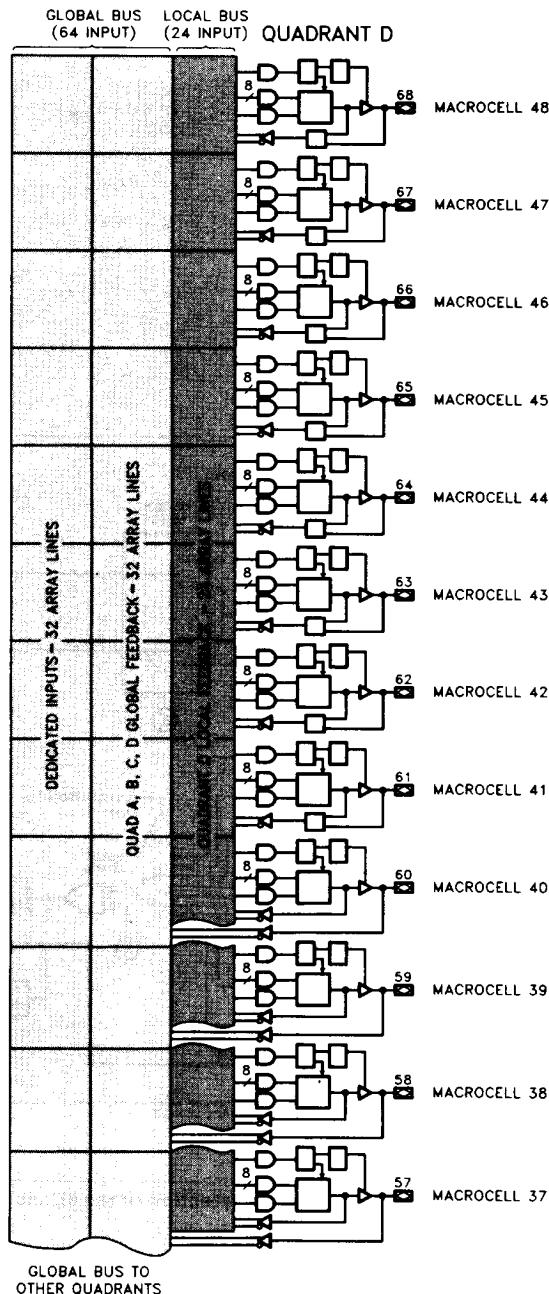


Figure 3. Basic Macrocell Architecture of the 5C180

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290111-4

Figure 4. Quadrant "D" Bus Interface

5C180 MACROCELLS

Within each 5C180 quadrant there are two different types of Macrocells; Local Macrocells, Figure 5, and Global Macrocells, Figure 6. Both types share an 88-input AND array and contain a total of ten product terms. Eight product terms are dedicated for logic implementation. One product term is reserved for Asynchronous Clear to the Macrocell register. The remaining product term is used for Output Enable/Asynchronous Clock implementation. Each 5C180 product term represents an 88-input AND gate. The I/O Architecture Control Block provides each Macrocell with both combinatorial and registered I/O configurations.

Local Macrocells provide one feedback path into the AND array. Combinatorial, registered or pin feedback may be selected from the Feedback Select Multiplexer. The selected feedback signal is then routed to the quadrant local bus. Therefore, the Local Macrocell feedback communicates only to Macro-

rocells within the same quadrant. There are a total of 32 Local Macrocells within the 5C180, with eight per quadrant.

Local macrocells are divided into two groups: General Macrocells and Enhanced Macrocells. The Enhanced Macrocells are architecturally identical to the General Macrocells but operate at higher speeds. These speed differences are reflected in the specification tables.

Global Macrocells contain two independent feedback paths to the AND array. Combinatorial or registered feedback is supplied to the local bus and pin feedback is supplied to the global bus. The "dual feedback" capability allows the Macrocell to be used for internal logic functions as well as a dedicated input pin. To obtain this configuration, the output buffer must be disabled. If the Global Macrocell I/O pin is not being used as a dedicated input, the Macrocell logic may be fed back along the global bus allowing routing to any of the 5C180's 48 Macrocells. There are 16 Global Macrocells contained in the 5C180, four per quadrant.

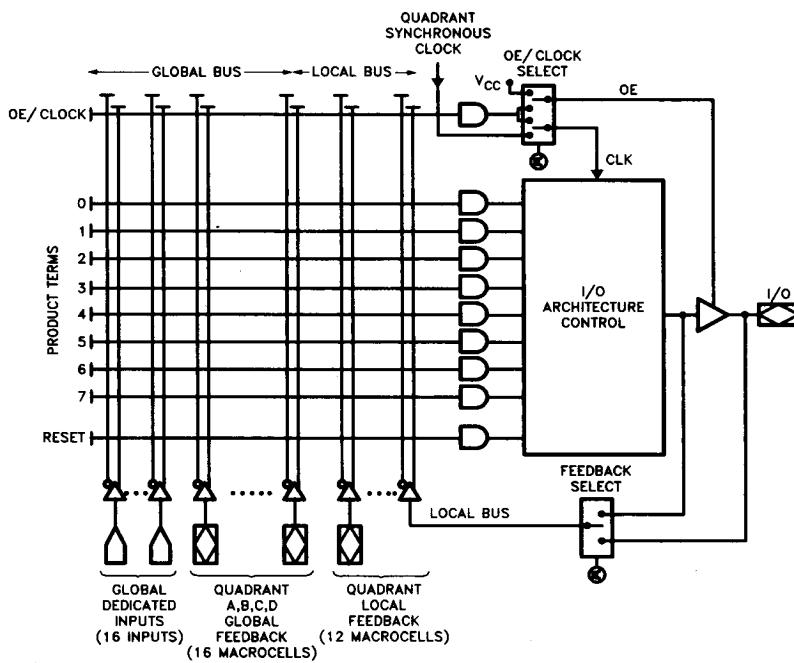


Figure 5. Local Macrocell Logic Array

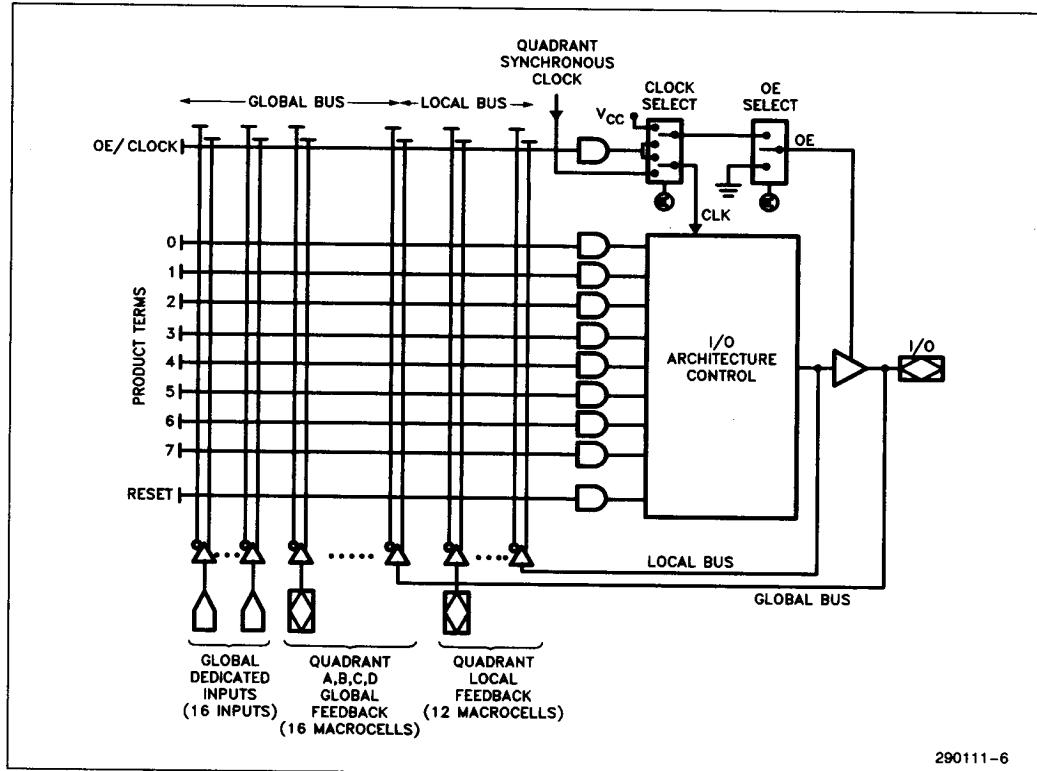


Figure 6. Global Macrocell Logic Array

MACROCELL LOGIC CONFIGURATIONS

Combinatorial Selection

In the Combinatorial configuration, eight product terms are ORed together to generate the output signal. The Invert Select EPROM bit controls output polarity and the Output Enable buffer is product-term controlled. The Feedback Select allows the user to choose combinatorial, I/O (pin) or no feedback to the respective local and global buses.

REGISTER SELECTION

The advanced I/O architecture of the 5C180 allows four different register types along with combinatorial output as illustrated in Figures 8a-8e. The register types include a T, D, JK, or SR Flip-Flop and each Macrocell I/O structure may be independently configured. In addition, all registers have an individual asynchronous RESET control from a dedicated

product term derived in the AND array. When this dedicated product term is a logical one, the Macrocell register is immediately cleared to a logical zero independent of the register clock. The RESET function occurs automatically on power-up.

The four different register types shown in Figures 7b-7e are described below:

D- or T-type Flip-Flops

When either a D- or T-type Flip-Flop is configured as part of the I/O structure, all eight of the product terms into the Macrocell are ORed together and fed into the register input.

JK or SR Registers

When either a JK or SR register is configured, the eight product terms are shared among two OR gates (one for the J or S input and the other for the K or R input). The allocation for these product terms for each of the register inputs is optimized by the iPLDS II development software.

Buried Logic Selection

For Global Macrocells, if no output is selected, the logic may be “buried” and the I/O pin can be used as an additional dedicated input. The use of “dual feedback” is accomplished by tri-stating the Output Enable Buffer. Thus, up to 16 additional dedicated inputs may be added without sacrificing the Macrocell internal logic.

In the erased state, the I/O architecture is configured for combinatorial active low output with I/O (pin) feedback.

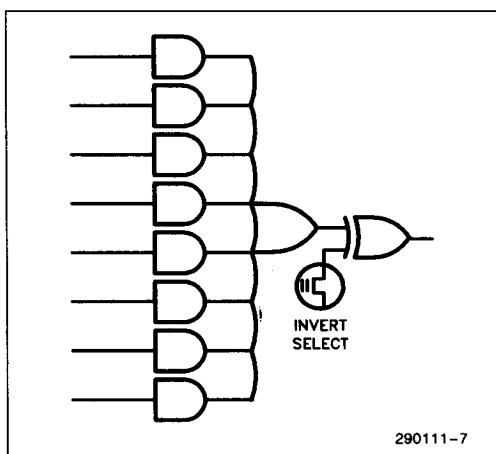


Figure 7a. Combinatorial I/O Configuration

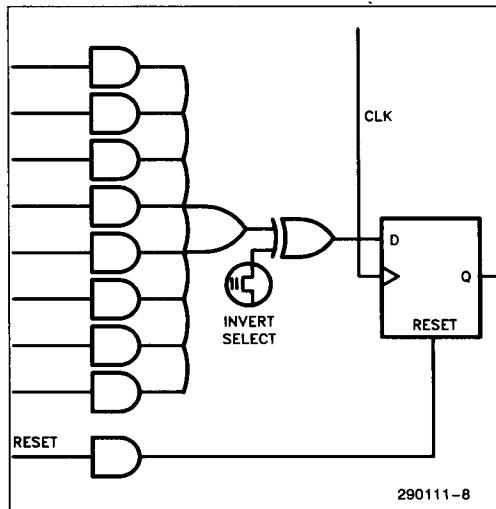


Figure 7b. D-Type Flip-Flop Register Configuration

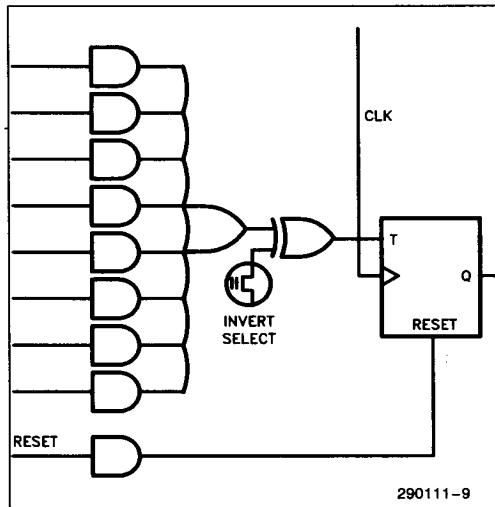


Figure 7c. Toggle (T-Type) Flip-Flop Register Configuration

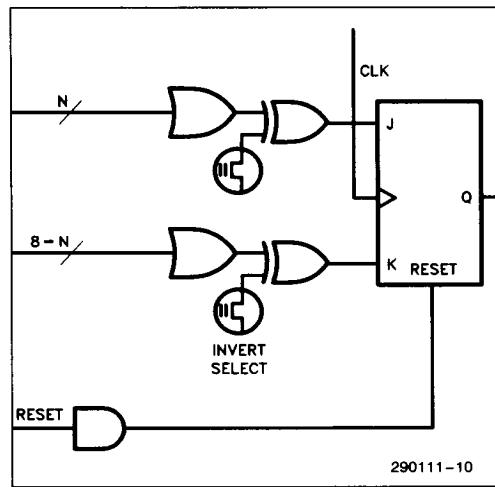


Figure 7d. JK Flip-Flop Register Configuration

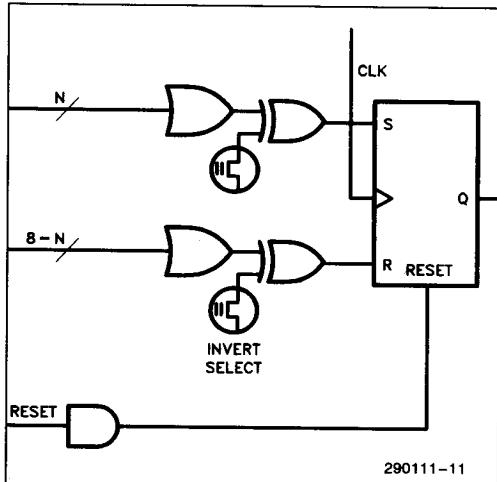


Figure 7e. SR Flip-Flop Register Configuration

MACROCELL OE/CLK SELECT

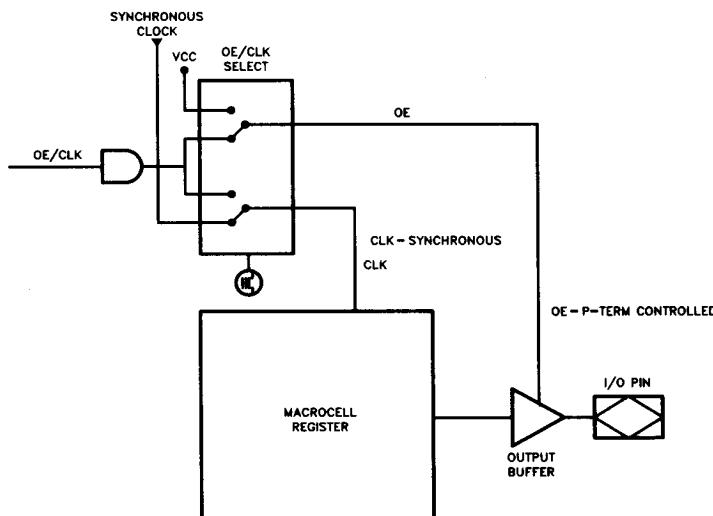
Each 5C180 register may be clocked synchronously or asynchronously. Figure 8a and 8b shows the modes of operation provided by the OE/CLK Select Multiplexers for both Local and Global Macrocells.

The operation of each multiplexer is controlled by EPROM bits and may be individually configured for each 5C180 Macrocell.

In Mode 0, the three-state output buffer is controlled by a single product term. If the output of the AND gate is a logical true then the output buffer is enabled. If a logical false resides on the output of the AND gate then the output buffer is seen as high impedance. In this mode the Macrocell flip-flop may be clocked by its quadrant synchronous clock input. In the erased state, the 5C180 is configured as Mode 0.

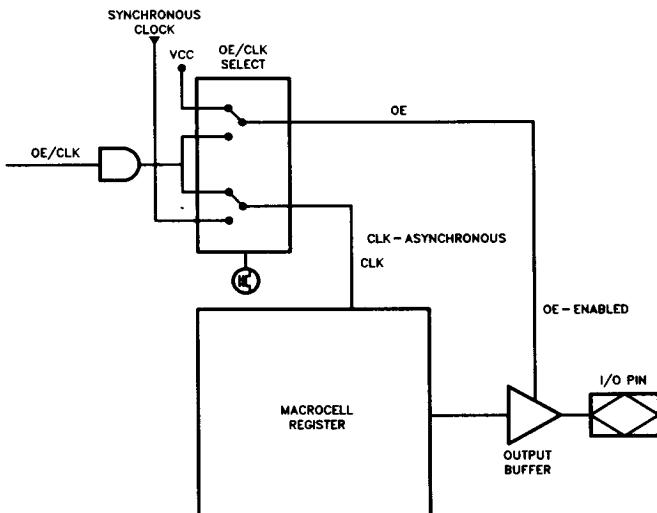
In Mode 1, the Output Buffer is always enabled. The Macrocell flip-flop now may be triggered from an asynchronous clock signal generated by the Macrocell product term. This mode allows individual clocking of flip-flops from any available signal in the quadrant AND array. Because both true and complement signals reside in the AND array, the flip-flops may be clocked by positive- or negative-going signals at any input pin. With the clock now controlled by a product term, gate clock structures are also possible.

In Modes 2 and 3, the Output Buffer is always disabled. The Macrocell flip-flop may still be triggered from clock signals generated from the Macrocell product term or asynchronous clocks. This mode is only possible for Global Macrocells.



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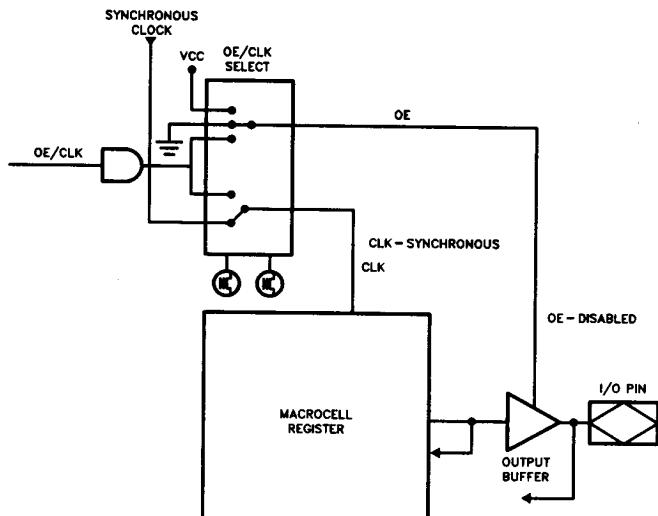
The register is clocked by the quadrant synchronous clock signal which is common to 11 other Macrocells. The output is enabled by the logic from the product term.



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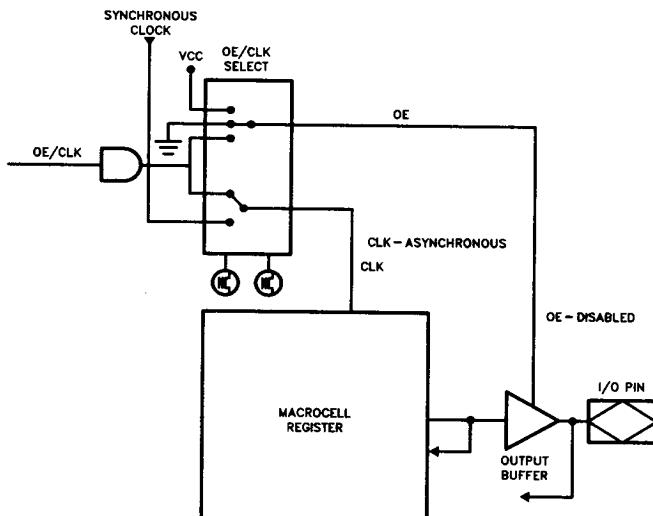
The output is permanently enabled and the register is clocked via the product term. This allows for gated clocks that may be generated from elsewhere in the 5C180.

Figure 8a. Local Macrocell OE/CLK Selection



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The output is permanently disabled and the register clocked by the quadrant synchronous clock signal. The pin can be used as an input while the register or combinational output can be fed back.



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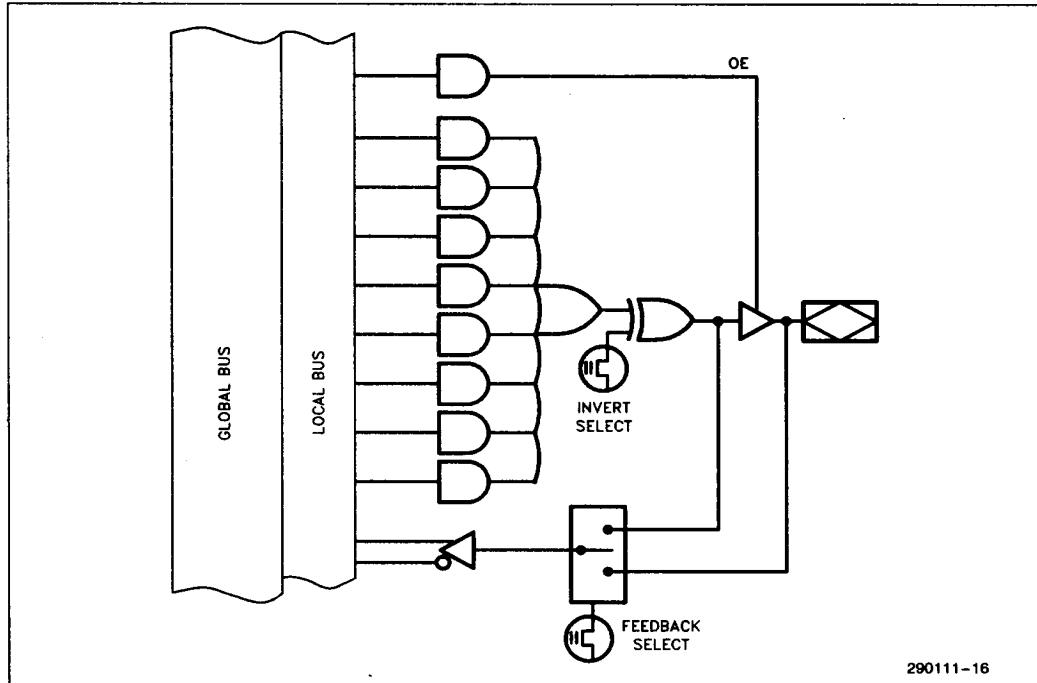
The output is permanently disabled and the register is clocked via the product term. This allows gated clocks that may be generated elsewhere in the 5C180. The pin can be used as an input while the register or combinational output can be fed back.

Figure 8b. Global Macrocell Additional OE/CLK Selection

MACROCELL LOGIC + I/O CONFIGURATIONS

The 5C180 Input/Output Architecture provides each Macrocell with over 50 possible I/O configurations.

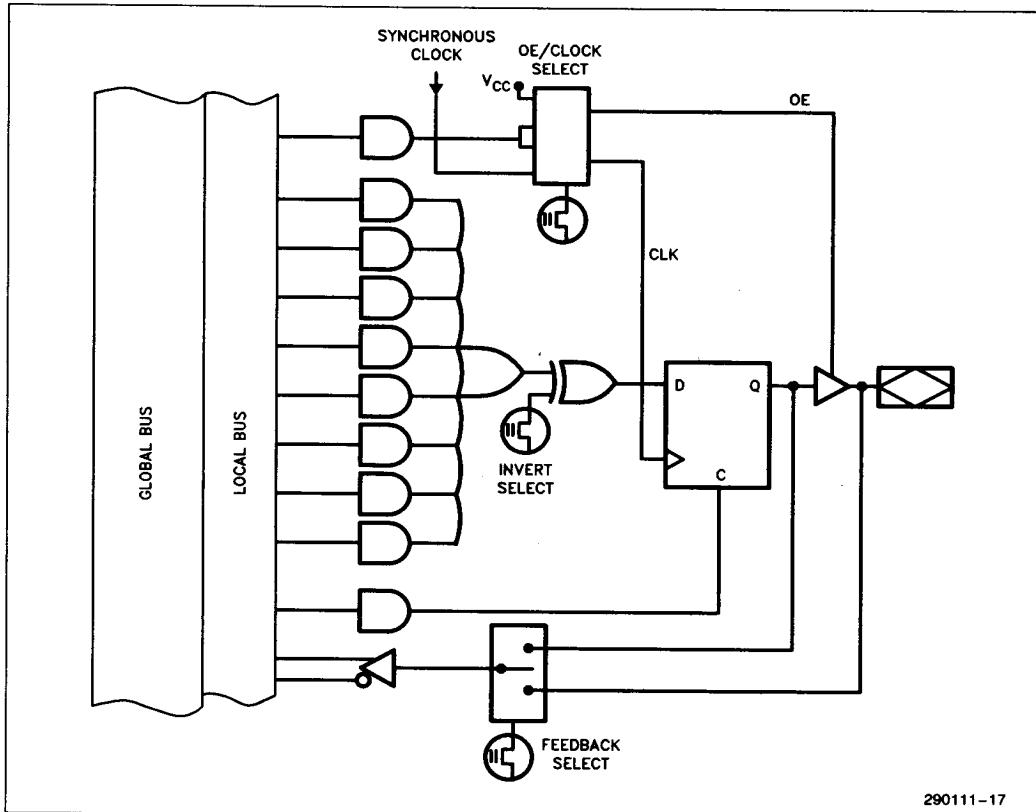
Figures 9 and 10 show the 5C180 basic I/O configurations for both the Local and Global Macrocells. Along with combinatorial, four register types are available. Each Macrocell may be independently programmed.



COMBINATORIAL I/O Selection

Output/Polarity	Feedback	Bus
Combinatorial/High	Comb, Pin, None	Local
Combinatorial/Low	Comb, Pin, None	Local
None	Comb	Local
None	Pin	Local

Figure 9. Local Macrocell I/O Configurations



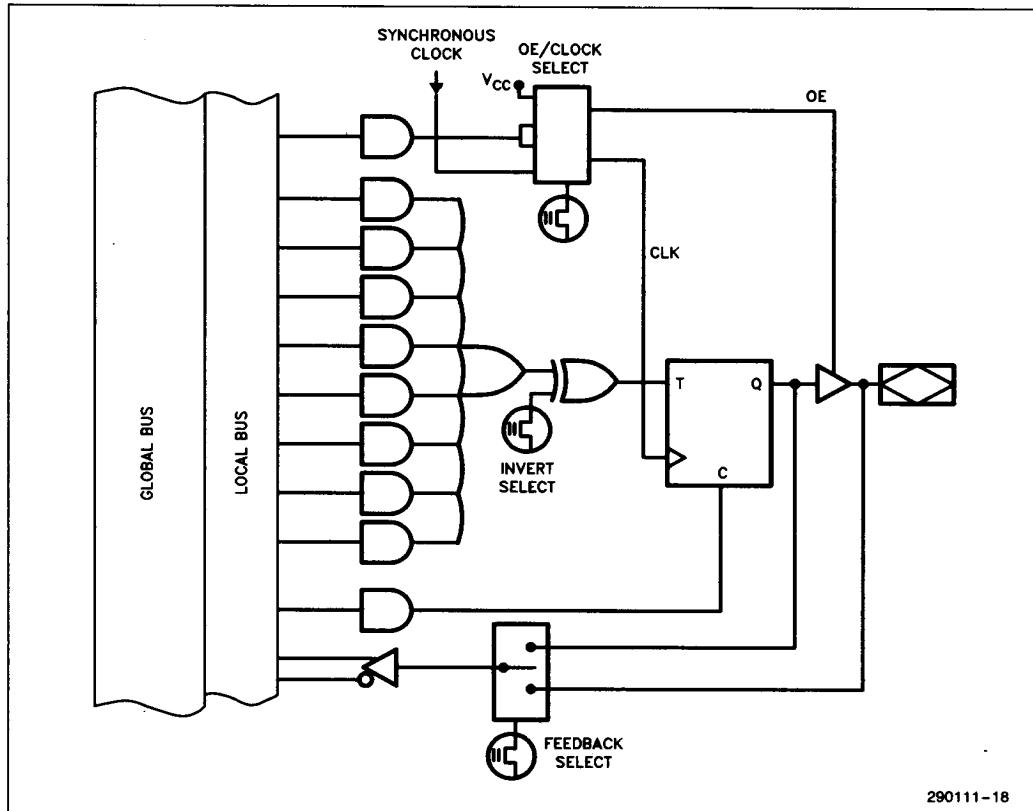
D-TYPE FLIP-FLOP I/O Selection

Output/Polarity	Feedback	Bus
D-Register/High	D-Register, Pin, None	Local
D-Register/Low	D-Register, Pin, None	Local
None	D-Register	Local
None	Pin	Local

Function Table

D	Q _n	Q _{n+1}
0	0	0
0	1	0
1	0	1
1	1	1

Figure 9. Local Macrocell I/O Configurations (Continued)



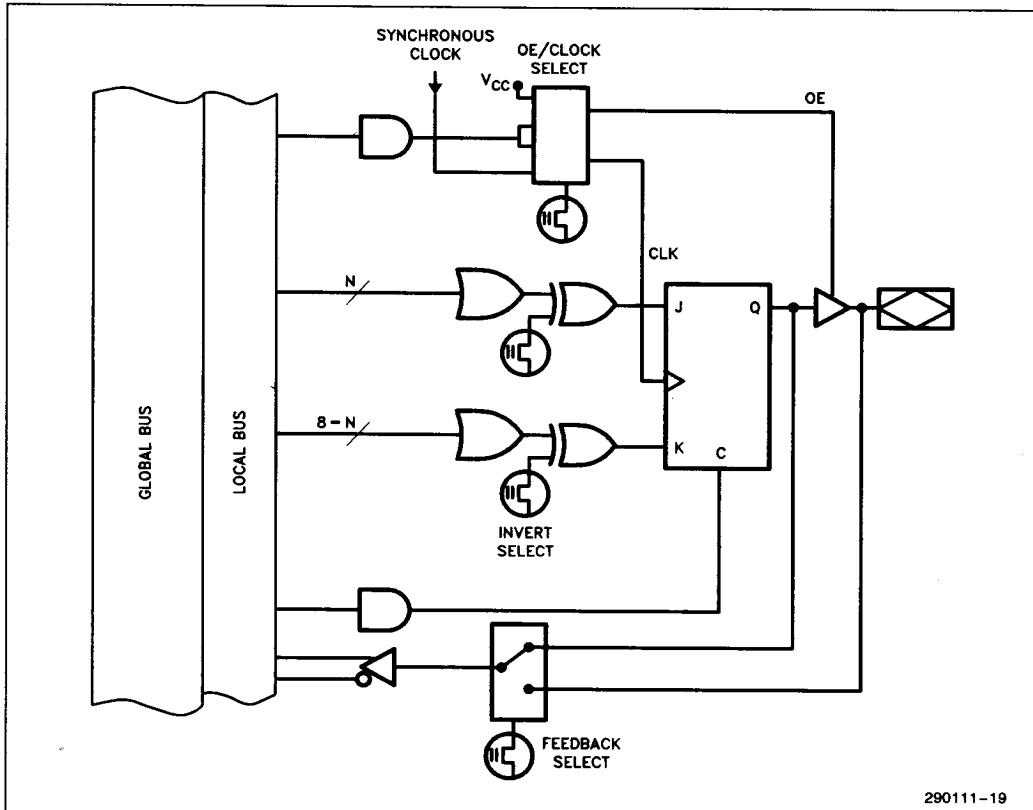
TOGGLE FLIP-FLOP I/O Selection

Output/Polarity	Feedback	Bus
T-Register/High	T-Register, Pin, None	Local
T-Register/Low	T-Register, Pin, None	Local
None	T-Register	Local
None	Pin	Local

Function Table

T	Q _n	Q _{n+1}
0	0	0
0	1	1
1	0	1
1	1	0

Figure 9. Local Macrocell I/O Configurations (Continued)



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JK FLIP-FLOP

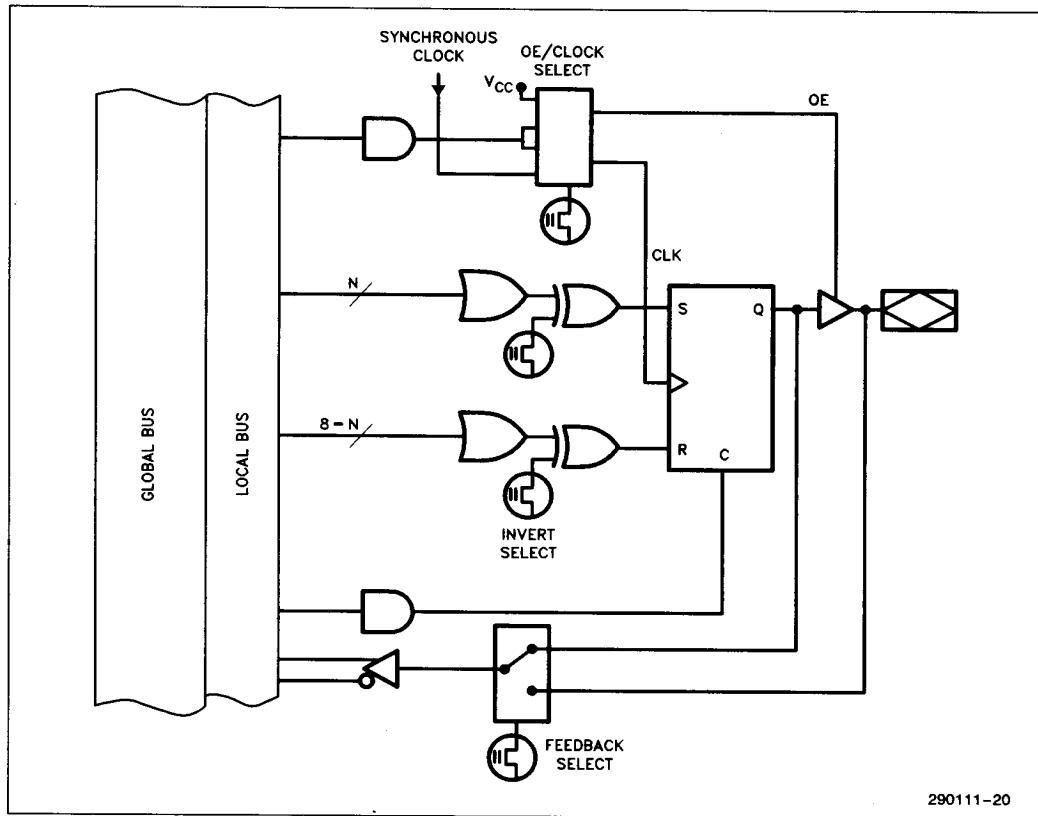
I/O Selection

Output/Polarity	Feedback	Bus
JK Register/High	JK Register, None	Local
JK Register/Low	JK Register, None	Local
None	JK Register	Local

Function Table

J	K	Q_n	Q_{n+1}
0	0	0	0
0	0	1	1
0	1	0	0
0	1	1	0
1	0	0	1
1	0	1	1
1	1	0	1
1	1	1	0

Figure 9. Local Macrocell I/O Configurations (Continued)



SR FLIP-FLOP

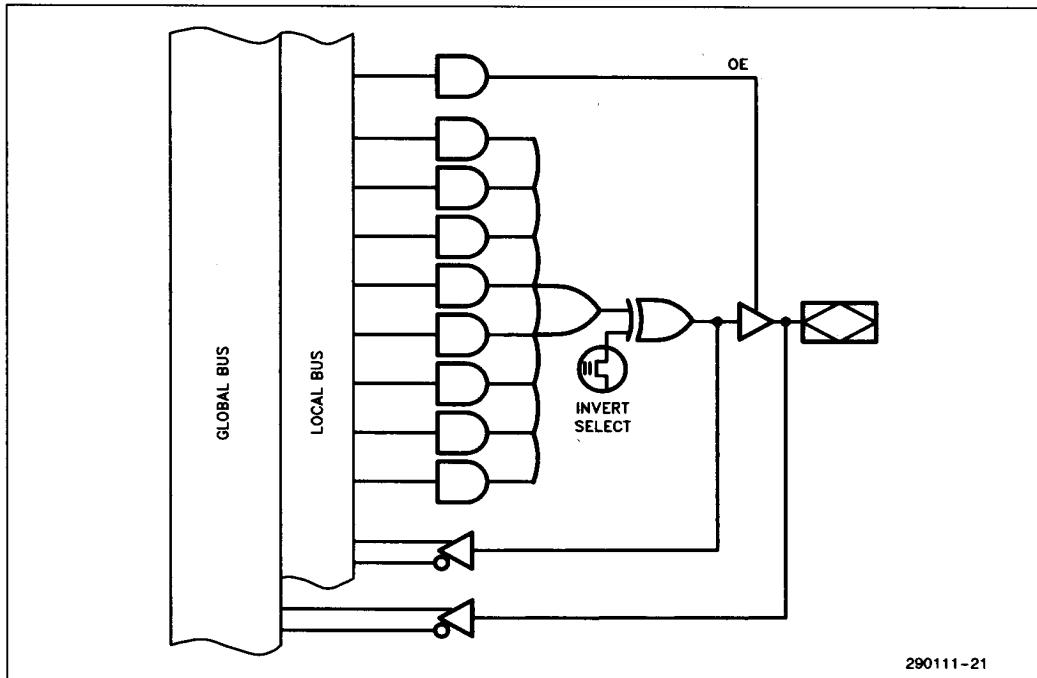
I/O Selection

Output/Polarity	Feedback	Bus
SR Register/High	SR Register, None	Local
SR Register/Low	SR Register, None	Local
None	SR Register	Local

Function Table

S	R	Q _n	Q _{n + 1}
0	0	0	0
0	0	1	1
0	1	0	0
0	1	1	0
1	0	0	1
1	0	1	1

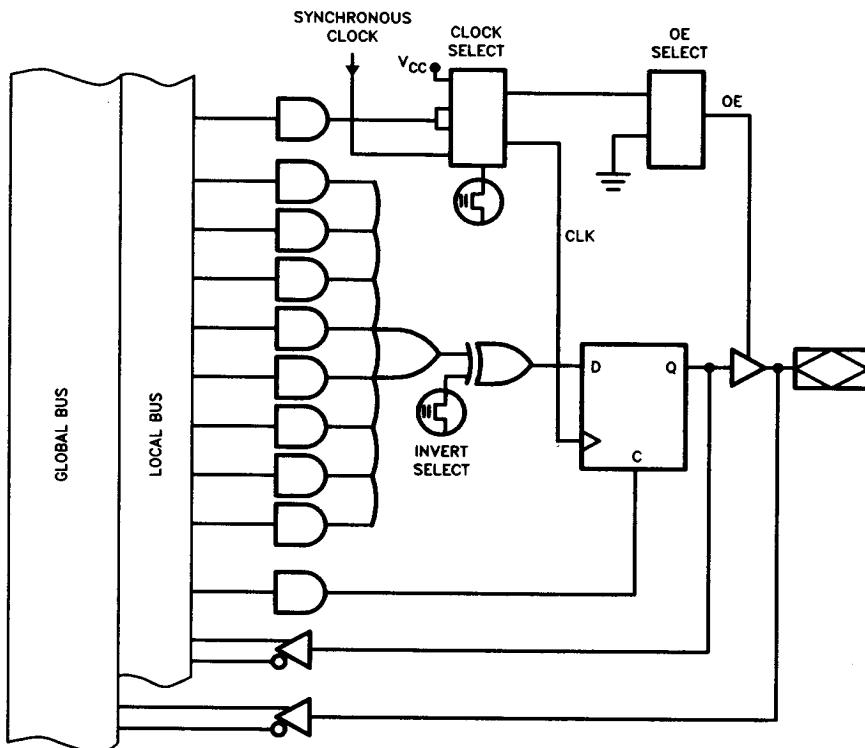
Figure 9. Local Macrocell I/O Configurations (Continued)



COMBINATORIAL I/O Selection

Output/Polarity	Feedback	Bus
Combinatorial/High	Comb, Pin, None	Local, Global
Combinatorial/Low	Comb, Pin, None	Local, Global
None	Comb	Local, Global
None	Pin	Global
None	Comb/Pin	Local/Global

Figure 10. Global Macrocell I/O Configurations



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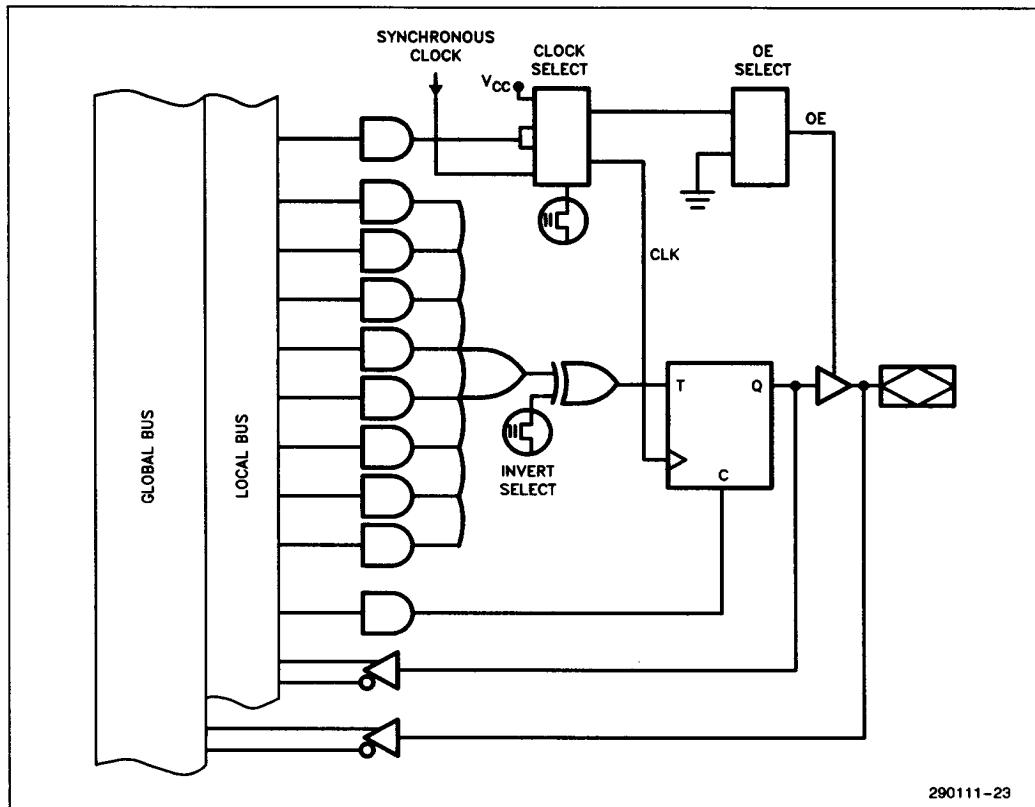
D-TYPE FLIP-FLOP

Output/Polarity	Feedback	Bus
D-Register/High	D-Register, Pin, None	Local, Global
D-Register/Low	D-Register, Pin, None	Local, Global
None	D-Register	Local, Global
None	Pin	Global
None	D-Register/Pin	Local/Global

Function Table

D	Q_n	Q_{n+1}
0	0	0
0	1	0
1	0	1
1	1	1

Figure 10. Global Macrocell I/O Configurations (Continued)



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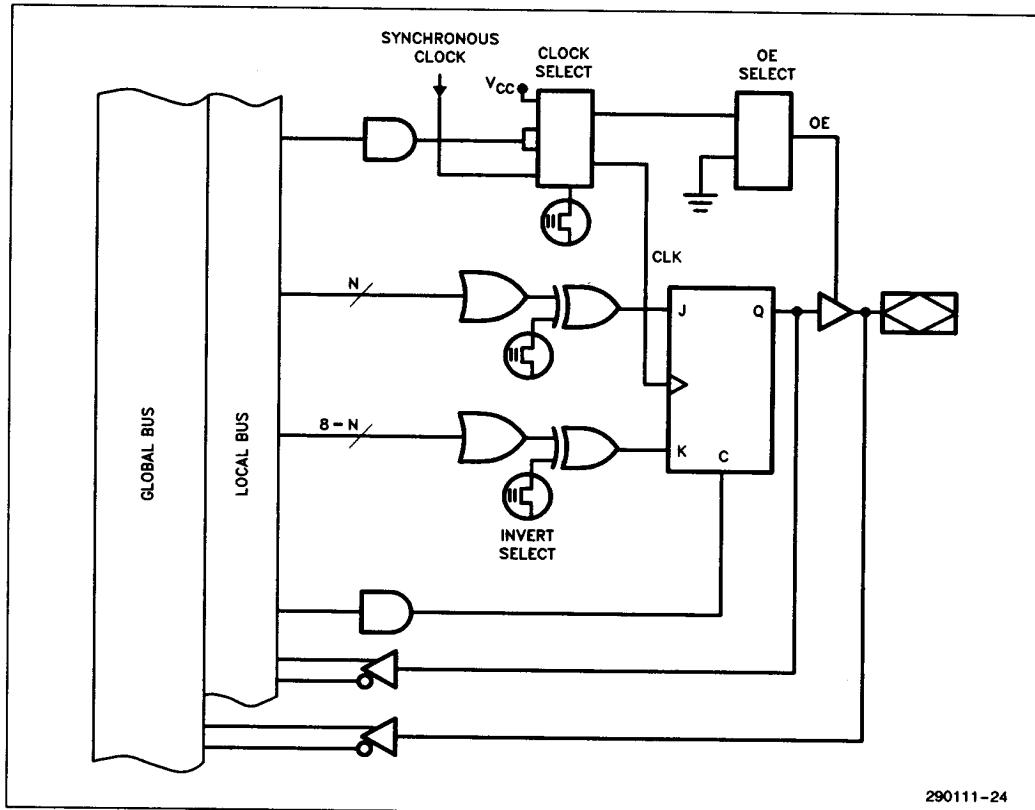
TOGGLE FLIP-FLOP I/O Selection

Output/Polarity	Feedback	Bus
T-Register/High	T-Register, Pin, None	Local, Global
T-Register/Low	T-Register, Pin, None	Local, Global
None	T-Register	Local, Global
None	Pin	Global
None	T-Register/Pin	Local/Global

Function Table

T	Q _n	Q _{n+1}
0	0	0
0	1	1
1	0	1
1	1	0

Figure 10. Global Macrocell I/O Configurations (Continued)



JK FLIP-FLOP

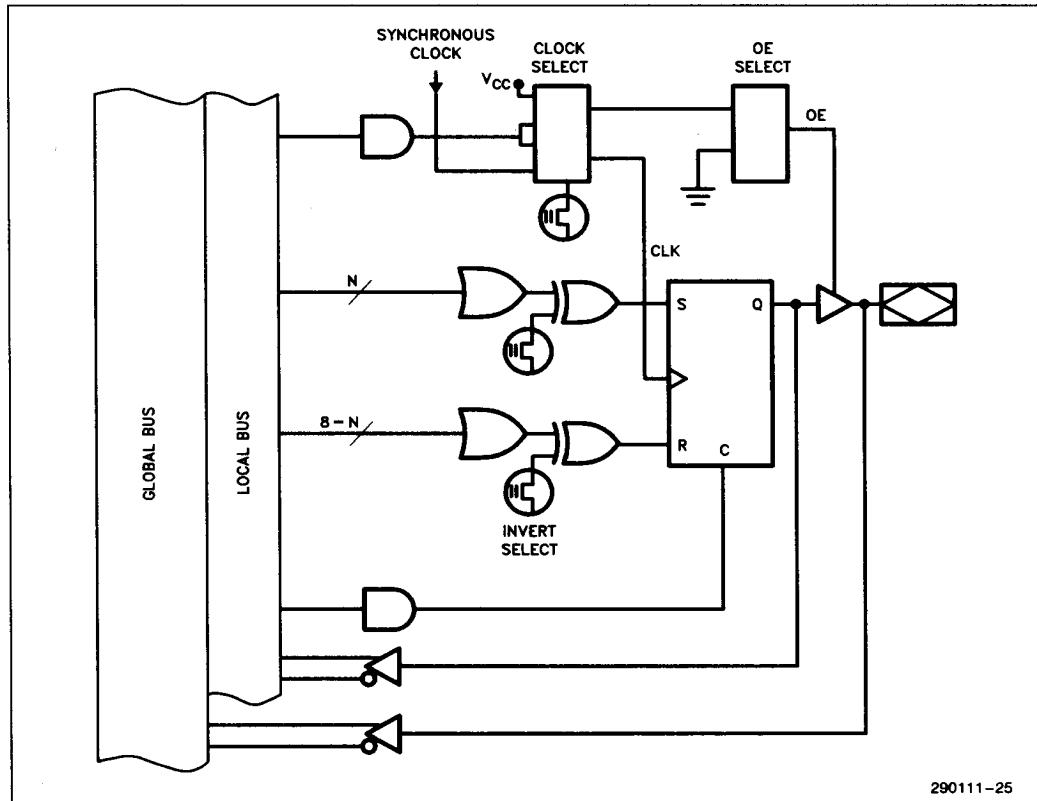
I/O Selection

Output/Polarity	Feedback	Bus
JK Register/High	JK Register, None	Local, Global
JK Register/Low	JK Register, None	Local, Global
None	JK Register	Local
None	JK Register/Pin	Local/Global

Function Table

J	K	Q _n	Q _{n+1}
0	0	0	0
0	0	1	1
0	1	0	0
0	1	1	0
1	0	0	1
1	0	1	1
1	1	0	1
1	1	1	0

Figure 10. Global Macrocell I/O Configurations (Continued)



290111-25

SR FLIP-FLOP**I/O Selection**

Output/Polarity	Feedback	Bus
SR Register/High	SR Register, None	Local, Global
SR Register/Low	SR Register, None	Local, Global
None	SR Register	Local
None	SR Register/Pin	Local/Global

Function Table

S	R	Q _n	Q _{n+1}
0	0	0	0
0	0	1	1
0	1	0	0
0	1	1	0
1	0	0	1
1	0	1	1

Figure 10. Global Macrocell I/O Configurations (Continued)

AUTOMATIC STAND-BY MODE

The 5C180 contains a programmable bit, the Turbo Bit, that optimizes operation for speed or for power savings. When the Turbo Bit is programmed (TURBO = ON), the device is optimized for maximum speed. When the Turbo Bit is not programmed (TURBO = OFF), the device is optimized for power savings by entering standby mode during periods of inactivity.

Figure 11 shows the device entering standby mode approximately 100 ns after the last input transition. When the next input transition is detected, the device returns to active mode. Wakeup time adds an additional 30 ns to the propagation delay through the device as measured from the first input. No delay will occur if an output is dependent on more than one input and the last of the inputs changes after the device has returned to active mode.

After erasure, the Turbo Bit is unprogrammed (OFF); automatic standby mode is enabled. When the Turbo Bit is programmed (ON), the device never enters standby mode.

ERASED-STATE CONFIGURATION

Prior to programming, the I/O structure is configured for combinatorial active low output with input (pin) feedback.

PROGRAMMING CHARACTERISTICS

Initially, all the EPROM control bits of the 5C180 are connected. Each of the connected control bits are selectively disconnected by programming the EPROM cells into their "on" state. Programming voltage and waveform specifications are available by request from Intel to support programming of the 5C180.

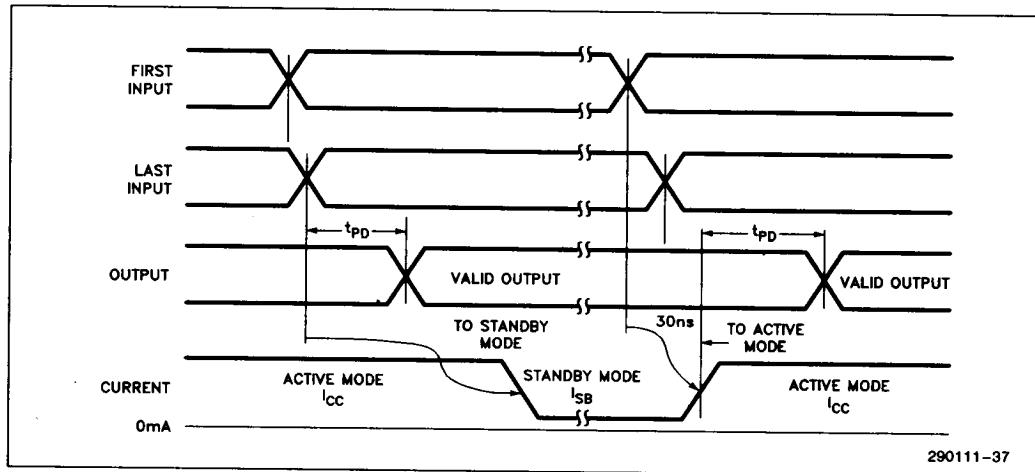


Figure 11. 5C180 Standby and Active Mode Transitions

Intelligent Programming Algorithm

The 5C180 supports the Intelligent Programming Algorithm which rapidly programs Intel PLDs using an efficient and reliable method. The Intelligent Programming Algorithm is particularly suited to the production programming environment. This method ensures reliability as the incremental program margin of each bit is continually monitored to determine when the bit has been successfully programmed.

FUNCTIONAL TESTING

Since the logical operation of the 5C180 is controlled by EPROM elements, the device is completely testable. Each programmable EPROM bit controlling the internal logic is tested using application-independent test program patterns. After testing, the devices are erased before shipment to customers. No post-programming tests of the EPROM array are required.

The testability and reliability of EPROM-based programmable logic devices is an important feature over similar devices based on fuse technology. Fuse-based programmable logic devices require a use to perform post-programming tests to insure proper programming. These tests must be done at the device level because of the cumulative error effect. For example, a board containing ten devices each possessing a 2% device fallout translates into an 18% fallout at the board level (it should be noted that programming fallout of fuse-based programmable logic devices is typically 2% or higher).

DESIGN RECOMMENDATIONS

For proper operation, it is recommended that all input and output pins be constrained to the voltage range $GND < (V_{IN} \text{ or } V_{OUT}) < V_{CC}$. Unused inputs and I/Os should be tied to V_{CC} or GND to minimize device power consumption. Reserved pins (as indicated in the logic compiler REPORT file) should be left floating (no connect) so that the pin can attain the appropriate logic level. A power supply decoupling capacitor of at least $0.2 \mu F$ must be connected directly between V_{CC} and GND.

As with all CMOS devices, ESD handling procedures should be used with this device to prevent damage during programming, assembly, and test.

DESIGN SECURITY

A single EPROM bit provides a programmable design security feature that controls the access to the data programmed into the device. If this bit is set, a proprietary design within the device cannot be copied. This EPROM security bit enables a higher degree of design security than fused-based devices since programmed data within EPROM cells is invisible even to microscopic evaluation. The EPROM security bit, along with all the other EPROM control bits, will be reset by erasing the device.

LATCH-UP IMMUNITY

All of the input, I/O, and clock pins of the 5C180 have been designed to resist latch-up which is inherent in inferior CMOS structures. The 5C180 is designed with Intel's proprietary CMOS II-E EPROM process. Thus, each of the 5C180 pins will not experience latch-up with currents up to ± 100 mA and voltages ranging from $-1V$ to $(V_{CC} + 1V)$. Furthermore, the programming pin is designed to resist latch-up to the 13.5V maximum device limit.

SOFTWARE SUPPORT

Full logic compilation and functional simulation for the 5C180 is supported by PLDshell Plus software.

PLDshell Plus design software is Intel's user-friendly design tool for μ PLD design. PLDshell Plus allows users to incorporate their preferred text editor, programming software, and additional design tools into an easy-to-use, menued design environment that includes Intel's PLDasm logic compiler and simulation software along with disassembly, conversion, and translation utilities. The PLDasm compiler and simulator software accepts industry-standard PDS source files that express designs as Boolean equations, truth tables, or state machines. On-line help, datasheet briefs, technical notes, and error message information, along with waveform viewing/printing capability make the design task as easy as possible. PLDshell Plus software is available from Intel Literature channels or from your local Intel sales representative.

Tools that support schematic capture and timing simulation for the 5C180 are available. Please refer to the "Development Tools" section of the Programmable Logic handbook.

The 5C180 is also supported by third-party logic compilers such as ABEL*, CUPL*, PLDesigner*, Log/IC, etc. Programming support is provided by third-party programmer companies such as Data

I/O, Logic Devices, STAG, etc. Please refer to the "Third-Party Support" lists in the *Programmable Logic* handbook for complete information and vendor contacts.

ORDERING INFORMATION

t_{PD} (ns)	t_{CO} (ns)	f_{MAX} (MHz)	Order Code	Package	Operating Range
70	29	20.8	N5C180-70	PLCC	Commercial
75	30	19.6	N5C180-75	PLCC	Commercial
90	35	16.1	N5C180-90	PLCC	Commercial
75	30	19.6	TN5C180-75	PLCC	Industrial

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage ⁽¹⁾	-2.0	7.0	V
V _{PP}	Programming Supply Voltage ⁽¹⁾	-2.0	13.5	V
V _I	DC Input Voltage ⁽¹⁾⁽²⁾	-0.5	V _{CC} + 0.5	V
t _{stg}	Storage Temperature	-65	+150	°C
t _{amb}	Ambient Temperature ⁽³⁾	-10	+85	°C

NOTICE: This is a production data sheet. The specifications are subject to change without notice.

*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

NOTES:

1. Voltages with respect to ground.
2. Minimum DC input is -0.5V. During transitions, the inputs may undershoot to -2.0V or overshoot to +7.0V for periods less than 20 ns under no load conditions.
3. Under bias. Extended temperature versions are also available.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	4.75	5.25	V
V _{IN}	Input Voltage	0	V _{CC}	V
V _O	Output Voltage	0	V _{CC}	V
T _A	Operating Temperature	0	+70	°C
t _R ⁽⁴⁾	Input Rise Time		500	ns
t _F ⁽⁴⁾	Input Fall Time		500	ns

NOTE:

4. t_R and t_F for clocks is 250 ns.

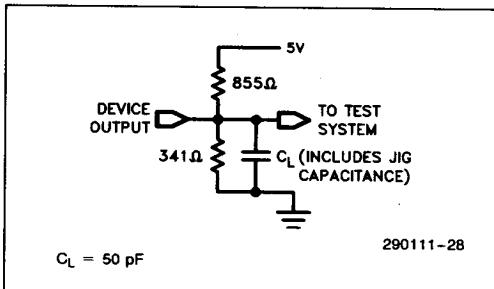
D.C. CHARACTERISTICS $T_A = 0^\circ \text{ to } +70^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$

Symbol	Parameter/Test Conditions	Min	Typ	Max	Unit
$V_{IH}^{(5)}$	High Level Input Voltage	2.0		$V_{CC} + 0.3$	V
$V_{IL}^{(5)}$	Low Level Input Voltage	-0.3		0.8	V
$V_{OH}^{(6)}$	High Level Output Voltage $I_O = -4.0 \text{ mA D.C.}, V_{CC} = \text{min.}$	2.4			V
V_{OL}	Low Level Output Voltage $I_O = 4.0 \text{ mA D.C.}, V_{CC} = \text{min.}$			0.45	V
I_I	Input Leakage Current $V_{CC} = \text{max.}, \text{GND} < V_{IN} < V_{CC}$			± 10	μA
I_{OZ}	Output Leakage Current $V_{CC} = \text{max.}, \text{GND} < V_{OUT} < V_{CC}$			± 10	μA
$I_{SC}^{(7)}$	Output Short Circuit Current $V_{CC} = \text{max.}, V_{OUT} = 0.5\text{V}$		20	30	mA
$I_{SB}^{(8)}$	Standby Current $V_{CC} = \text{max.}, V_{IN} = V_{CC} \text{ or GND},$ Standby mode		35	150	μA
I_{CC}	Power Supply Current $V_{CC} = \text{max.}, V_{IN} = V_{CC} \text{ or GND},$ No load, Input Freq. = 1 MHz Active mode (Turbo = Off), Device prog. as four 12-bit Ctrs.		30	45	mA

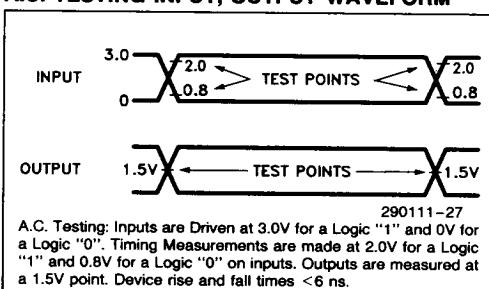
NOTES:

- Absolute values with respect to device GND; all over and undershoots due to system or tester noise are included.
- I_O at CMOS levels (3.84 V) = -2 mA
- Not more than 1 output should be tested at a time. Duration of that test must not exceed 1 second.
- With Turbo Bit Off, device automatically enters standby mode approximately 100 ns after last input transition.

A.C. TESTING LOAD CIRCUIT



A.C. TESTING INPUT, OUTPUT WAVEFORM



CAPACITANCE

Symbol	Parameter	Min	Typ	Max	Unit	Conditions			
C_{IN}	Input Capacitance			15	pF	$V_{IN} = 0V, f = 1.0 \text{ MHz}$			
C_{OUT}	Output Capacitance			15	pF	$V_{OUT} = 0V, f = 1.0 \text{ MHz}$			
C_{CLK}	Clock Pin Capacitance			25	pF	$V_{OUT} = 0V, f = 1.0 \text{ MHz}$			
C_{VPP}	V_{PP} Pin Capacitance			160	pF	$CLK2, V_{OUT} = 0V, f = 1.0 \text{ MHz}$			

A.C. CHARACTERISTICS $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{CC} = 5V \pm 5\%$, Turbo Bit On⁽⁹⁾

Symbol	From	To	5C180-70 EP1800-2			5C180-75			5C180-90 EP1800			Non-Turbo Mode ⁽¹¹⁾	Unit
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max		
t_{PD1}	Input ⁽¹²⁾	Comb. Output			65			70			85	+ 30	ns
t_{PD2}	I/O ⁽¹²⁾	Comb. Output			70			75			90	+ 30	ns
t_{PD2e}	I/O ⁽¹³⁾	Comb. Output			65			70			85	+ 30	ns
$t_{PZX}^{(10)}$	I or I/O	Output Enable			70			75			90	+ 30	ns
$t_{PXZ}^{(10)}$	I or I/O	Output Disable			70			75			90	+ 30	ns
t_{CLR}	Asynch. Reset	Q Reset			70			75			90	+ 30	ns

NOTES:

9. Typ. Values are at $T_A = 25^\circ\text{C}$, $V_{CC} = 5V$, Active Mode.10. t_{PZX} and t_{PXZ} are measured at $\pm 0.5V$ from steady state voltage as driven by spec. output load. t_{PXZ} is measured with $C_L = 5 \text{ pF}$.

11. If device is operated with Turbo Bit Off (Non-Turbo Mode) and the device has been inactive for approx. 100 ns, increase time by amount shown.

SYNCHRONOUS CLOCK MODE A.C. CHARACTERISTICS

 $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{CC} = 5V \pm 5\%$, Turbo Bit On⁽⁹⁾

Symbol	Parameter	5C180-70 EP1800-2			5C180-75			5C180-90 EP1800			Non-Turbo Mode ⁽¹¹⁾	Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max		
f_{MAX}	Max Frequency $1/(t_{CH} + t_{CL})$ —No Feedback			20.8			19.6			16.1		MHz
f_{CNT}	Max. Count Frequency $1/t_{CNT}$ —With Feedback			16.1			15.1			12.2		MHz
t_{SU1}	Input Setup Time to Clk ⁽¹²⁾	48		51			62			+ 30		ns
t_{SU2}	I/O Setup Time to Clk ⁽¹²⁾	53		56			67			+ 30		ns
t_{SU2e}	I/O Setup Time to Clk ⁽¹³⁾	48		51			62			+ 30		ns
t_H	I or I/O Hold after Clk High	0		0			0					ns
t_{CO}	Clk High to Output Valid			29			30			35		ns
t_{CNT}	Register Output Feedback to Register Input— Internal Path	62		66			82			+ 30		ns
t_{CH}	Clk High Time	24		25			30					ns
t_{CL}	Clk Low Time	24		25			30					ns

ASYNCHRONOUS CLOCK MODE A.C. CHARACTERISTICS

 $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, Turbo Bit On⁽⁹⁾

Symbol	Parameter	5C180-70 EP1800-2			5C180-75 EP1800			5C180-90 EP1800			Non-Turbo Mode ⁽¹¹⁾	Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max		
f _{AMAX}	Max. Frequency $1/(t_{ACH} + t_{ACL})$ - No Feedback			20.8			20			16.6		MHz
f _{ACNT}	Max. Frequency $1/t_{ACNT}$ - With Feedback			16.1			15.1			12.2		MHz
t _{ASU1}	Input Setup Time to Asynch. Clock ⁽¹²⁾	17			19			23			+30	ns
t _{ASU2}	I/O Setup Time to Asynch. Clock ⁽¹²⁾	22			25			28			+30	ns
t _{AH}	Input or I/O Hold to Asynch. Clock	30			30			30				ns
t _{ACO}	Asynch. Clk to Output Valid			70			75			90		ns
t _{ACNT}	Register Output Feedback to Register Input - Internal Path	62			66			82			+30	ns
t _{ACH}	Asynch. Clk High Time	24			25			30				ns
t _{ACL}	Asynch. Clk Low Time	24			25			30				ns

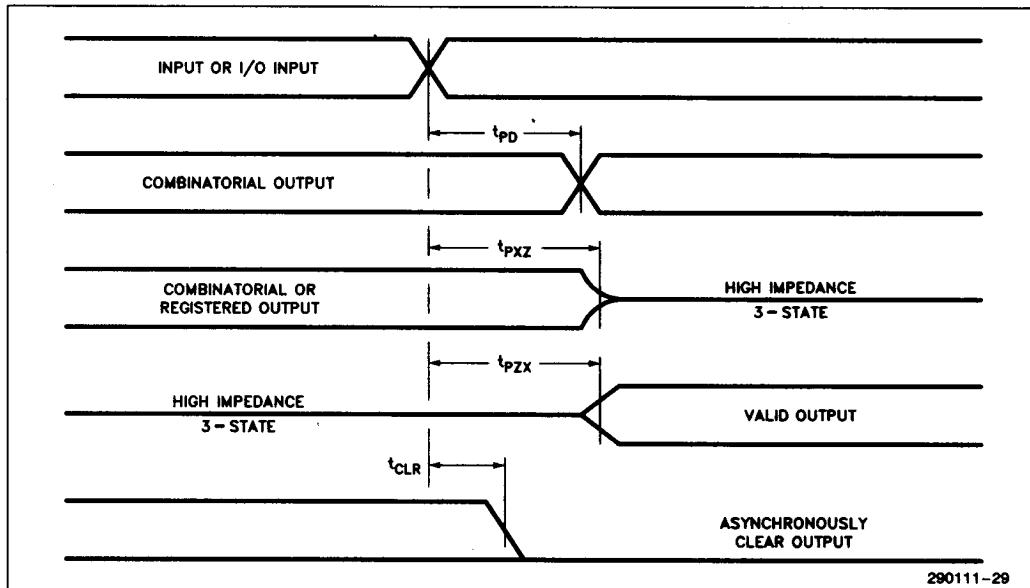
NOTES:

12. For General and Global Macrocells.
13. For Enhanced Macrocells.

2

SWITCHING WAVEFORMS

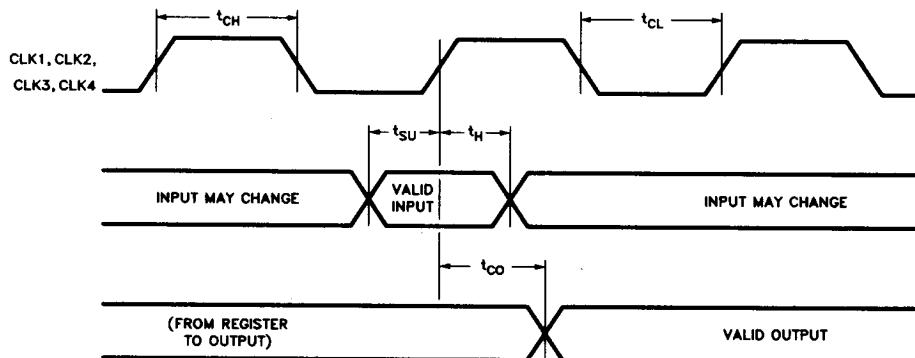
COMBINATORIAL MODE



290111-29

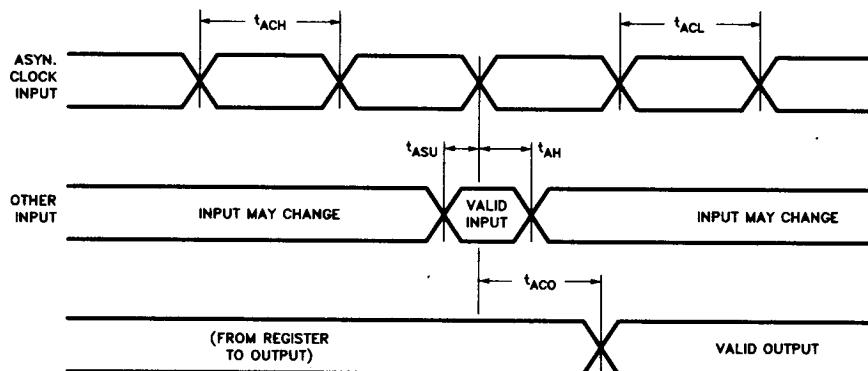
SWITCHING WAVEFORMS (Continued)

SYNCHRONOUS CLOCK MODE

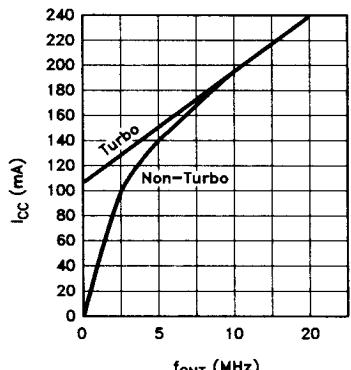


290111-30

ASYNCHRONOUS CLOCK MODE



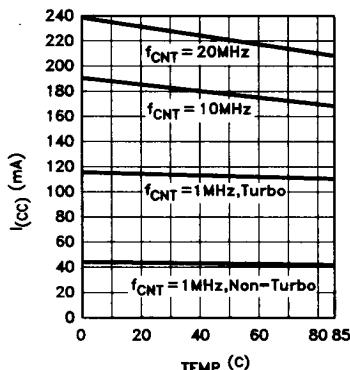
290111-31



$T_A = 0^\circ\text{C}$, $V_{CC} = 5.25\text{V}$

290111-32

Current in Relation to Frequency

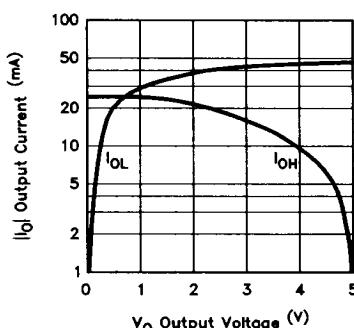


$V_{CC} = 5.25\text{V}$

290111-33

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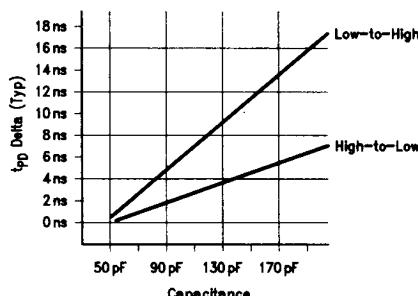
Current in Relation to Temperature



290111-34

Output Drive Current in Relation to Voltage

5C180 t_{PD} Derating vs Capacitive Loading

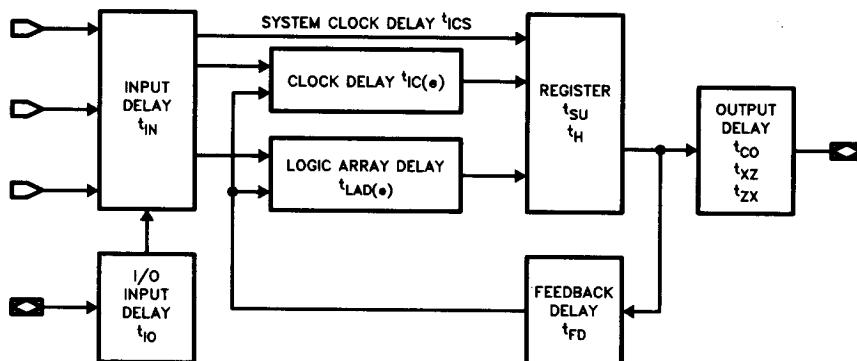


Conditions:
 $T_A = 25^\circ\text{C}$
 $V_{CC} = 5.0\text{V}$

290111-39

5C180 INTERNAL TIMING

The following internal timing model and specifications are provided to aid in determining the different timing parameters for all permutations of timing paths through the device. The mnemonics in the table represent *internal parameters* only and should not be confused with external timing parameters shown in previous tables, even though some mnemonics are the same.



290111-38

Symbol	Parameter	5C180-70 EP1800-2		5C180-75		5C180-90 EP1800		Non-Turbo Mode ⁽¹¹⁾		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input Pad and Buffer Delay	10		11		14		0		ns
t_{IO}	I/O Input Pad and Buffer Delay	5		5		5		0		ns
t_{LADe}	Enhanced Logic Array Delay	35		37		43		30		ns
t_{LAD}	Logic Array Delay	40		42		48		30		ns
t_{OD}	Output Buffer and Pad Delay	15		17		23		0		ns
t_{ZX}	Output Buffer Enable	15		17		23		0		ns
t_{XZ}	Output Buffer Disable	15		17		23		0		ns
t_{SU}	Register Setup Time	12		13		18		0		ns
t_{HS}	Register Hold Time (System Clock)	0		0		0		0		ns
t_H	Register Hold Time	30		30		30		0		ns
t_{ICe}	Enhanced Clock Delay	35		37		43		30		ns
t_{IC}	Clock Delay	40		42		48		30		ns
t_{ICS}	System Clock Delay	4		4		4		0		ns
t_{FD}	Feedback Delay	10		11		16		-30		ns
t_{CLRe}	Enhanced Register Clear Time	35		37		43		30		ns
t_{CLR}	Register Clear Time	40		42		48		30		ns